


1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

416 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 26x26 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	LS-BGA416E-41 Drawing © 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Status: Released	Scale: 4:1	Rev: B
		Drawing: M.A. Fedde	Date: 12/19/11	
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